

Test beam preparation

Test beam

- Sensors, envelops, Kapton (HV, RO)
- Tungsten, frame
- FEB
- DAQ
- Mainframe
- Mechanics (cabling, cooling,...)

Sensors, envelops, kapton

- Sensors are in TAU :
 - 8 are mounted and ready (last TB)
 - Around 20 sensors not mounted and not tested
 - Kapton : needs to produce more
 - HV : same design
 - RO : maybe good to redesign it
- Envelops : produced at CERN

Tungsten, frames

- 25 tungsten plates are at CERN
- Frames :
 - How many are at cern ?
 - Who can mount the W on the frames ?

FEB : FLAME

- Chip (32 channels) will be available in quantity (~240)
- Readout board : 8 chip (one full sensor)
- Connection to sensors : ?
- Mechanics : to be study after PCB produced (thickness, weight,...)

FEB : APV

- Used in 2015 and 2016 TB. Saturated after few mips
- Actual charge divider : divide the signal by a constant factor -> we are loosing the small energy range
- New charge divider :
 - signal split in 2 : one with factor 1, one with factor >1 .
 - pros : no loose of any channel, cons : this use two times more channels
 - Design finish and first test done
 - Need to be produced for the TB

DAQ for FLAME

- Each FEB needs one zynq FPGA to handle it (which cable between FEB and FPGA?) : how many FPGA will be available
- Synchronization between FPGA boards : TLU based

DAQ for APV

- Exist and tested

Mainframe, mechanics,...

- Box to hold the layers : exists
- Modifications : ?

Timescale (no parallel work)

